

In the Claims:

Claims 1-11 (Cancelled)

12. (Original) A thermal head comprising:
- a thermal insulation layer on a radiative substrate;
 - a plurality of heating resistor elements on a top face of the thermal insulation layer;
 - a power supplier including an individual electrode and a common electrode connected to the heating resistor elements to supply power to a heating resistor; and
 - a protection layer that covers surfaces of at least the heating resistor elements and the power supplier,
- wherein the thermal insulation layer includes an organic thermal insulation layer having a polyimide resin, and
- wherein a thermal diffusion layer is formed on bottom faces of the heating resistor elements with interposition of an electric insulation film.
13. (Original) The thermal head according to claim 12, wherein the thermal diffusion layer comprises a high melting point metal.